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## Highlights

- Award-winning design optimizing efficiencies in energy, cooling and density for data centers
- Operational costs drastically reduced based on innovative shallow depth server form factor
- High performance computing embracing broad, flexible portfolio of offerings with simplified system management and tools.



# IBM System x iDataPlex dx360 M3

*Leading the server industry in energy, cooling and space efficiencies for data centers*

Designed for data centers that require high performance, yet are constrained on floor space, power and cooling infrastructure, the IBM® System x® iDataPlex® dx360 M3 provides an innovative, half-depth solution optimized for maximum density and incredible efficiency. Featuring the latest Intel® Xeon® Processor 5600 series with 16 DDR-3 DIMM sockets and two PCIe x16 Gen 2 slots, the dx360 M3 is easy to manage and delivers outstanding performance in a flexible platform that can be tailored to your data center's processing, storage or I/O needs.

For high performance computing, the dx360 M3 allows you to pack accelerated processing into the same power and cooling envelope as traditional servers, better utilizing floor space and optimizing the data center. The flexible design of the dx360 M3 integrates the right compute, storage or I/O capabilities required in your data center while optimizing density.

The innovative, shallow-depth form factor of the dx360 M3 reduces the airflow required across the components, lowering the power needed for cooling. High-efficiency power supplies, larger, better-optimized fans in the 2U chassis, and power management capabilities provide further efficiencies to minimize the dx360 M3's power requirements.

The dx360 M3 is simple to manage on a server level or at a rack level as part of an iDataPlex rack. IBM ToolsCenter provides common management across all System x servers, making the dx360 M3 easy to incorporate into your data center.





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IBM Systems and Technology Group  
Route 100  
Somers, NY 10589

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## IBM System x iDataPlex dx360 M3 at a glance

<b>Form factor/height</b>	Half-depth, 2U Flex chassis or 3U storage chassis
<b>Processor</b> (max)	Intel® Xeon® 5600 series up to 3.06 GHz (6-core) or 3.20 GHz (4-core)
<b>Number of processors</b> (std/max)	2 CPU, 2 GPU adapters (optional)
<b>Cache</b> (max)	4 MB to 12 MB
<b>Memory</b> (max)	Up to 192 GB DDR-3 1333 MHz via 16 DIMM slots
<b>Expansion slots</b>	Up to 2 slots PCIe x16 electrical/x16 mech (Gen 2), 2 x8 PCIe
<b>Disk bays</b> (total)	Up to 8 2.5" (2U) or 12 3.5" (3U storage density)
<b>Maximum internal storage</b>	24.0 TB (3U storage chassis)
<b>Interconnect Fabric Adapters</b>	Ethernet—Integrated 1 Gb dual-port Ethernet, 10 Gb (optional); Fibre Channel—8 GB dual-port HBA (optional); InfiniBand—QDR or DDR single- or dual-port HCA (optional); solid-state drives—160 or 320 GB High IOPS PCIe (optional)
<b>Power supply</b> (std/max)	900 W high efficiency nonredundant (per two servers) 550 W high efficiency nonredundant (per two servers) 750 W N+N redundant (per two servers)
<b>Hot-swap components</b>	Hot-swap HDDs in 3U storage dense configuration
<b>RAID support</b>	RAID-0, -1, -5, -6, -10, -50, -60 via optional I/O controller
<b>Systems management</b>	IBM Systems Director including IBM Systems Director Active Energy Manager™, Integrated Management Module (IMM) with optional remote KVM support, integrated 10/100 configurable management port
<b>Operating systems</b>	Red Hat Enterprise Linux® versions 6, 5 and 4, SUSE Linux Enterprise Server versions 11 and 10, Microsoft® Windows Server 2008 R2, 2008 (Datacenter, HPC, Enterprise and Web), VMware Infrastructure 3.5 and VMware vSphere 4.1
<b>Limited warranty</b>	3-year customer replaceable unit and onsite limited warranty

## For more information

Contact your IBM representative or IBM Business Partner or visit:  
[ibm.com/systems/x/hardware/idataplex.html](http://ibm.com/systems/x/hardware/idataplex.html)